



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR PowerPAK® SO-8L					
STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
BOND INT	360	180 000	200 °C + N2	0	0.00
HAST	1384	138 400	130 °C, 85 % RH	0	0.00
Power Cycle	82	1 230 000	DELTA T _J = 100 °C	0	0.00
Pressure Pot	2194	210 624	121°, 15 PSIG	0	0.00
Solder DUNK	420	1260	260 °C, 10 s	0	0.00
Solderability	105	840	883 M2003	0	0.00
Temp. Cycle	4713	2 506 024	-55 °C to 150 °C	0	0.00